

WHAT IS CLAIMED IS:

1. An electronic device cooling system, comprising:
a heat exchange unit;
at least one cooling interface disposed at a heat-transfer interface of an electronic device, said cooling interface being thermally coupled to said heat exchange unit; and
a heat exhaust thermally coupled to said heat exchange unit, said heat exhaust exhausting heat from said heat exchange unit to a remote location from said electronic device.
2. The apparatus of claim 1, wherein said electronic device further comprises a plurality of heat-transfer interfaces wherein said heat-transfer interfaces include an ambient air inlet and a warm air outlet.
3. The apparatus of claim 2, wherein said cooling interface is disposed at said ambient air inlet.
4. The apparatus of claim 2, wherein said cooling interface is disposed at said warm air outlet.
5. The apparatus of claim 2, wherein a first cooling interface is disposed at said ambient air inlet of said electronic device, and a second cooling interface is disposed at said warm air outlet of said electronic device.
6. The apparatus of claim 5, wherein said first and second cooling interfaces comprise cooling coils.
7. The apparatus of claim 5, wherein said first and second cooling interfaces comprise cool air conduits.

8. The apparatus of claim 5, wherein said first cooling interface comprises a cool air conduit and said second cooling interface comprises cooling coils.

9. The apparatus of claim 5, wherein said first cooling interface comprises cooling coils and said second cooling interfaces comprises a cool air conduit.

10. The apparatus of claim 5, wherein said first and second cooling interfaces are disposed within said electronic device.

11. The apparatus of claim 1, further comprising a plurality of electronic devices and a plurality of cooling interfaces such that a cooling interface is disposed at a heat-transfer interface of each electronic device.

12. The apparatus of claim 1, further comprising a support structure wherein said electronic device and said cooling device are configured to be commonly supported by said support structure.

13. The apparatus of claim 12, wherein said support structure comprises a server rack.

14. The apparatus of claim 12, wherein said support structure is confined within a room and wherein said remote location is a location outside of said room.

15. The apparatus of claim 1, wherein said electronic device is a server.

16. An electronic device cooling assembly, comprising:
at least one electronic device having a plurality of heat-transfer interfaces;
a heat exchange unit having a heat exhaust;
wherein said heat exchange unit is configured to take heat from at least one of said heat-transfer interfaces; and

wherein said heat exhaust is configured to exhaust said heat taken from one of said heat-transfer interface at a remote location from said electronic device.

17. The apparatus of claim 16, wherein said heat-transfer interfaces comprise an ambient air inlet and a warm air outlet.

18. The apparatus of claim 17, further comprising a cooling interface of said heat exchange unit disposed at said ambient air inlet.

19. The apparatus of claim 17, further comprising a cooling interface of said heat exchange unit disposed at warm air outlet.

20. The apparatus of claim 17, wherein a first cooling interface of said heat exchange unit is disposed at said ambient air inlet of said electronic device, and a second cooling interface of said heat exchange unit is disposed at said warm air outlet of said electronic device.

21. The apparatus of claim 20, wherein said first and second cooling interfaces comprise cooling coils.

22. The apparatus of claim 20, wherein said first and second cooling interfaces comprise cool air conduits.

23. The apparatus of claim 20, wherein said first cooling interface comprises a cool air conduit and said second cooling interface comprises cooling coils.

24. The apparatus of claim 20, wherein said first cooling interfaces comprise cooling coils and said second cooling interfaces comprises a cool air conduit.

25. The apparatus of claim 16, further comprising a plurality of electronic devices.

26. The apparatus of claim 25, wherein said plurality of electronic devices comprises a plurality of servers.

27. The apparatus of claim 16, further comprising a support structure wherein said electronic device and said heat exchange unit are configured to be commonly supported by said support structure.

28. The apparatus of claim 27, wherein said support structure comprises a server rack.

29. The apparatus of claim 28, wherein said electronic device and said cooling device are substantially the same width.

30. The apparatus of claim 27, wherein said support structure is confined within a room and wherein said remote location is a location outside of said room.

31. A method of regulating the temperature of an assembly of electronic devices, comprising:

providing at least one electronic device having a heat-transfer interface;
providing a cooling unit in communication with said heat-transfer interface of said at least one electronic device; and
exhausting heat from said heat-transfer interface with said cooling unit to a remote location from said electronic device.

32. The method of claim 31, wherein said heat-transfer interface comprise an ambient air inlet and a warm air outlet.

33. The method of claim 32, further comprising connecting said cooling unit with said ambient air inlet.

34. The method of claim 32, further comprising connecting said cooling unit with said warm air outlet.

35. The method of claim 32, further comprising connecting said cooling unit to both said ambient air inlet and said warm air outlet.

36. The method of claim 31, wherein said electronic device comprises a server.

37. The method of claim 36, wherein said at least one electronic device comprises a plurality of servers, said method further comprising coupling said cooling unit with each of said plurality of servers.

38. The method of claim 31, further comprising supporting said electronic device and said cooling device with a common support structure.

39. The method of claim 38, wherein said support structure comprises a server rack.

40. The method of claim 39, wherein said electronic device and said cooling unit are of substantially the same width.

41. The method of claim 39, further comprising confining said support structure within a room, wherein said remote location is a location outside of said room.

42. An electronic device cooling system, comprising:
cooling means located at a plurality of electronic devices for removing heat from air entering or exiting said electronic devices; and
exhaust means for exhausting said heat to a remote location from said electronic devices.

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43. The system of claim 42, further comprising support means for supporting said cooling means and said electronic devices.

45. The system of claim 42, wherein said cooling means comprises means for removing heat from air entering said electronic devices.

46. The system of claim 42, wherein said cooling means comprises means for removing heat from air exiting said electronic devices.

47. 46. The system of claim 42, wherein said cooling means comprises means for removing heat from air entering and exiting said electronic devices.